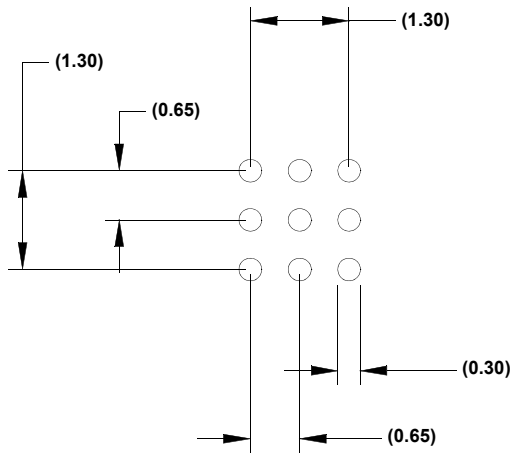
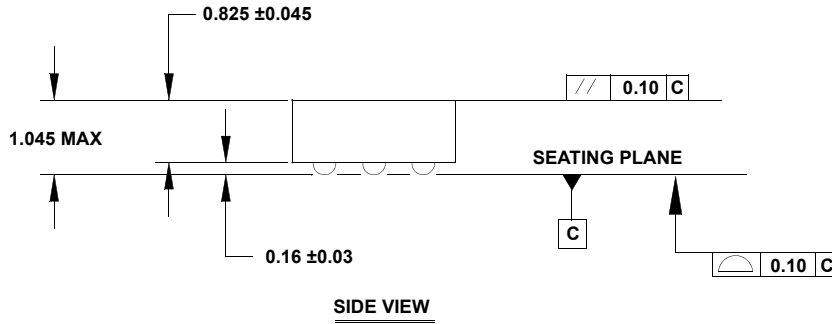
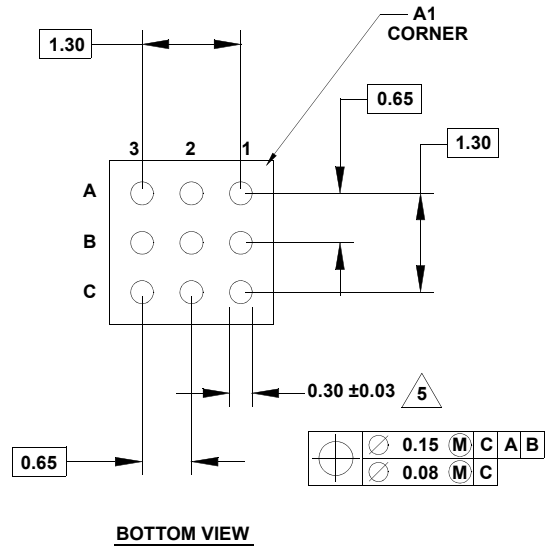
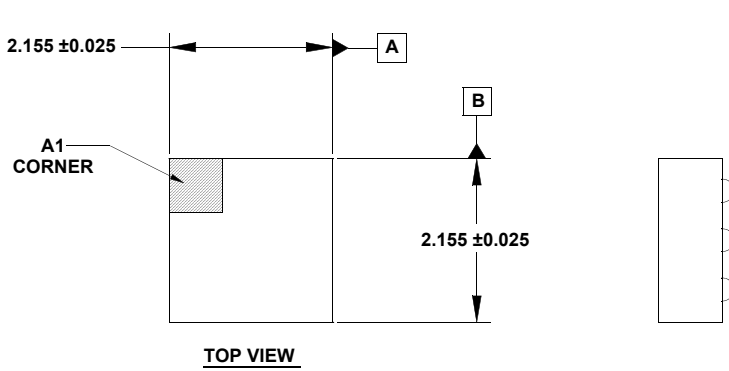


# Package Outline Drawing

## S3x3.9

3X3 ARRAY 9 BUMP OPTICAL CHIP SCALE PACKAGE (OCSF)

Rev 7, 10/10



**NOTES:**

1. Dimensions are in millimeters.  
Dimensions in ( ) for Reference only.
2. Dimensioning and tolerancing conform to ASME Y 14.5M-1994
3. Primary datum C and seating plane are defined by the spherical crowns of the contact balls.
4. Pin "A1" is marked on the top and bottom side adjacent to the A1 ball.
5. Dimension is measured at the maximum ball diameter.